

PA 6 C

CAST POLYAMIDE 6

Material description

PA 6 Cast is an inexpensive, highly crystalline and high molecular weight, non - modified thermoplastic with excellent mechanical strength values and high toughness. Compared with extruded polyamides, PA 6 G has a lower - stress and more homogeneous microstructure. PA 6 G is excellent for machining. The high moisture absorption of PA 6 G can lead to volume changes and to restrictions in its mechanical values as well as its dielectric strength.

Conformities

RoHS, REACH

Physical properties	Test method	Value	Unit
Density	DIN EN ISO 1183-1	1.15	g/cm3
Water absorbtion	DIN EN ISO 62	2.5	%
Sliding friction			
Abrasion resistance			

Mechanical properties	Test method	Value	Unit
Yield stress	DIN EN ISO 527	75	MPa
Elongation at break	DIN EN ISO 527	>45	%
Tensile modulus of elasticity	DIN EN ISO 527	3400	MPa
Notched impact strength	DIN EN ISO 527	>3	kJ/m2
Ball indentation hardness	DIN EN ISO 2039-1	180	MPa

Thermal properties	Test method	Value	Unit
Thermal conductivity	DIN 52612-2	0.25	W/(m*K)
Heat capacity	DIN 52612-1	1.7	kJ/(kg*K)
Coefficient of thermal expansion	DIN 53752	80	10 ⁻⁶ *K ⁻¹
Operating temperature short term		170	°C
Operating temperature long term		-40 bis 110	°C
Heat deflection temperature	DIN EN ISO 75 / A	95	°C
Flammability	UL 94, 3 mm	HB / V2	

Electrical properties	Test method	Value	Unit
Volume resistivity	IEC 60093	10 ¹⁵	Ω * cm
Surface resistivity	IEC 60093	10 ¹³	Ω * cm
Dielectric strength	IEC 60243	20	kV/mm
Comparative tracking index (CTI)	IEC 60112	600	CTI

These technical data have been determined as average values by our suppliers from many individual measurements. In all measurements, the test specimens were tested in the dry state. We pass on the data with reservation. The table does not claim to be complete or correct. Material technology is subject to constant further development. No rights or guarantees can be derived from it. Own tests are necessary because the environmental and operating conditions (humidity, temperature, mechanical forces, radiation and chemicals, etc.) set limits in the application.